Notification Number:	20190605001	**Notification Date:**	06/07/2019
Title:	DLPC34XX and DLPC150 Data Sheet Change		
Customer Contact:	Dlp-pcn-team@list.ti.com	**Dept:**	Quality Services
Change Type:			

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification for the below data sheet change.

	Change from	Change to
Pin Functions / System Power-Up and Power-Down Sequence	Longer mirror parking time of up to 500 µs	Longer mirror parking time of up to 20 ms

Refer to DLP® Pico™ DMD Chipset Parking Technical Advisory for more details. Data sheets will be updated by July 1, 2019 to reflect this change.

Reason for Change:

Clarify chipset power-down requirements for Normal Park operation.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Within the system power-down sequence, the maximum Normal Park time will be increased from 500 µs to 20 ms.

Changes to product identification resulting from this notification:

None

Product Affected:

DLPC3430CZVBR, DLPC3432CZVB, DLPC3433CZVB, DLPC3434CZVB, DLPC3435ZEZ, DLPC3435CZEZ, DLPC3436CZVB, DLPC3437CZEZ, DLPC3438CZEZ, DLPC3439CZEZ, DLPC3440CZEZ, DLPC150ZEZ, DLPC3479CZEZ, DLPC3478CZEZ, DLPC3470CZEZ

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
DLP® Products	Dlp-pcn-team@list.ti.com
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
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